

Product Data Sheet

DIAION™ SKT20L

DIAION™ SKT20L is a gel type strongly acidic cation exchange resin. It has standard cross-linkages and shows lower TOC and metal leakage. It is recommended for semiconductor UPW application.

Product

Grade Name	DIAION™ SKT20L
Type	Strong Acid Cation
Matrix	Styrene-DVB, Gel
Functional Group	Sulfonic acid
Ionic Form	H ⁺

Specification

Color and Shape	-	Brown Translucent Beads
Salt Splitting Capacity	meq/mL	1.7 min.
Water Content	%	50 - 60
Particle Size Distribution on 1180 µm	%	5 max.
Particle Size Distribution thr. 425 µm	%	1 max.
Effective Size	mm	0.45 min.
Uniformity Coefficient	-	1.6 max.
Ionic Form Conversion (H ⁺)	eq%	99.9 min.
Metal Content (Na)	ppb/dry-g	1000 max.
Metal Content (Ca)	ppb/dry-g	1000 max.
Metal Content (Fe)	ppb/dry-g	1000 max.
Metal Content (Zn)	ppb/dry-g	1000 max.
ΔTOC	ppb	5.0 max.
Outlet Resistivity	MΩ·cm	16 min.

Typical Properties

Shipping Density	g/L	790
Mean Particle Size	µm	710
Particle Density	g/mL	1.20
Total Swelling (Na ⁺ to H ⁺)	%	9



DIAION™ SKT20L

Recommended Operating Conditions

Maximum Operating Temperature	°C	120
Operating pH Range		0 - 14
Minimum Bed Depth	mm	800
Service Flow Rate	m/h	10 - 40
Regenerant		HCl
		H ₂ SO ₄
Regenerant Concentration	%	HCl 4 - 10
		H ₂ SO ₄ 1 - 4
Regenerant Level	g/L	30 - 150
Regenerant Flow Rate	m/h	2 - 10
Total Rinse Requirement	BV	2 - 10



DIAION™ SKT20L

Hydraulic Characteristics

The approximate pressure drop at various temperatures and flow rates for each meter of bed depth of DIAION™ SKT20L resin in normal down flow operation is shown in the graphs below.

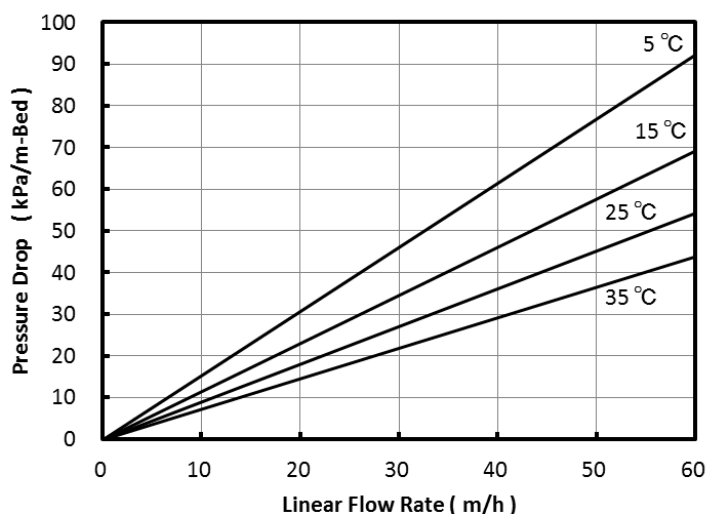


Fig. 1 Pressure Drop of SKT20L

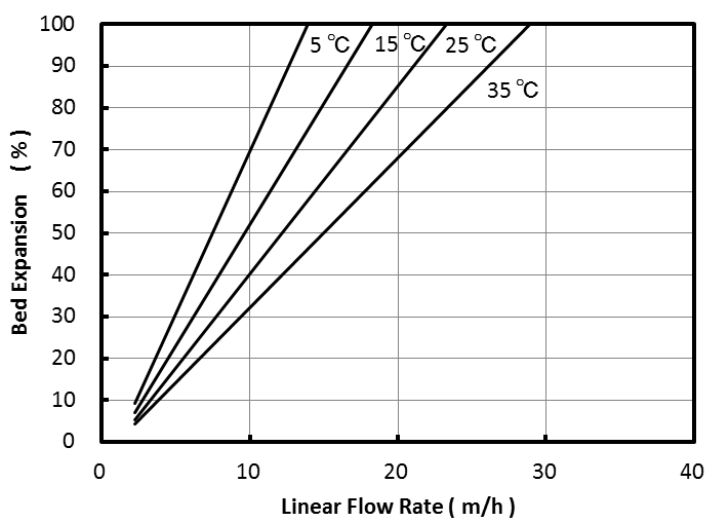


Fig. 2 Bed Expansion of SKT20L

DIAION™ SKT20L

Rinse Performance

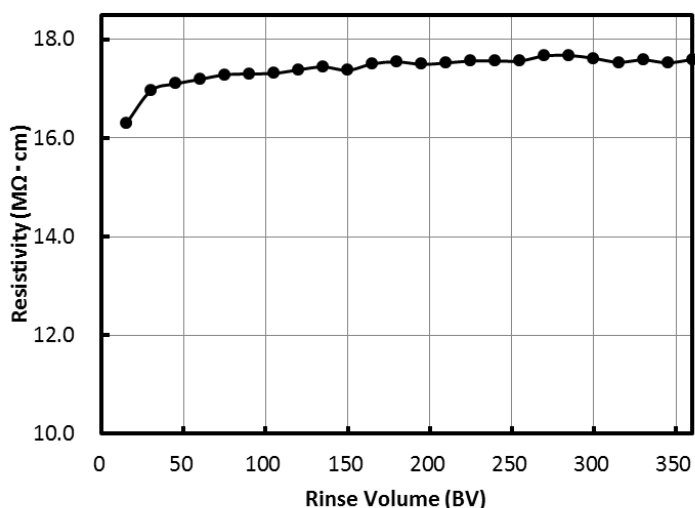


Fig. 3 Resistivity versus Rinse Volume for SKT20L

Flow rate : SV 30 (15 L/hr), Resin volume : 500 mL-R

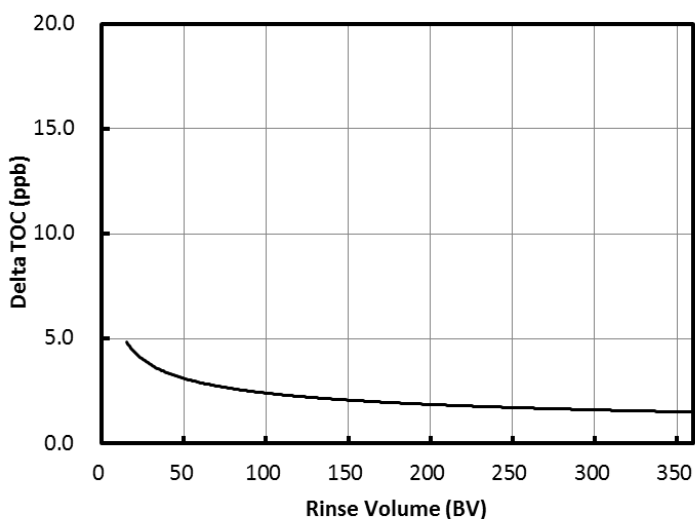


Fig. 4 Delta TOC versus Rinse Volume for SKT20L

Flow rate : SV 30 (15 L/hr), Resin volume : 500 mL-R

Notice

This information are given in good faith but without warranty, and this also applies where proprietary rights of third parties are involved. The application, use and processing of our products are beyond our control and therefore your own responsibility.